

# Figure 1

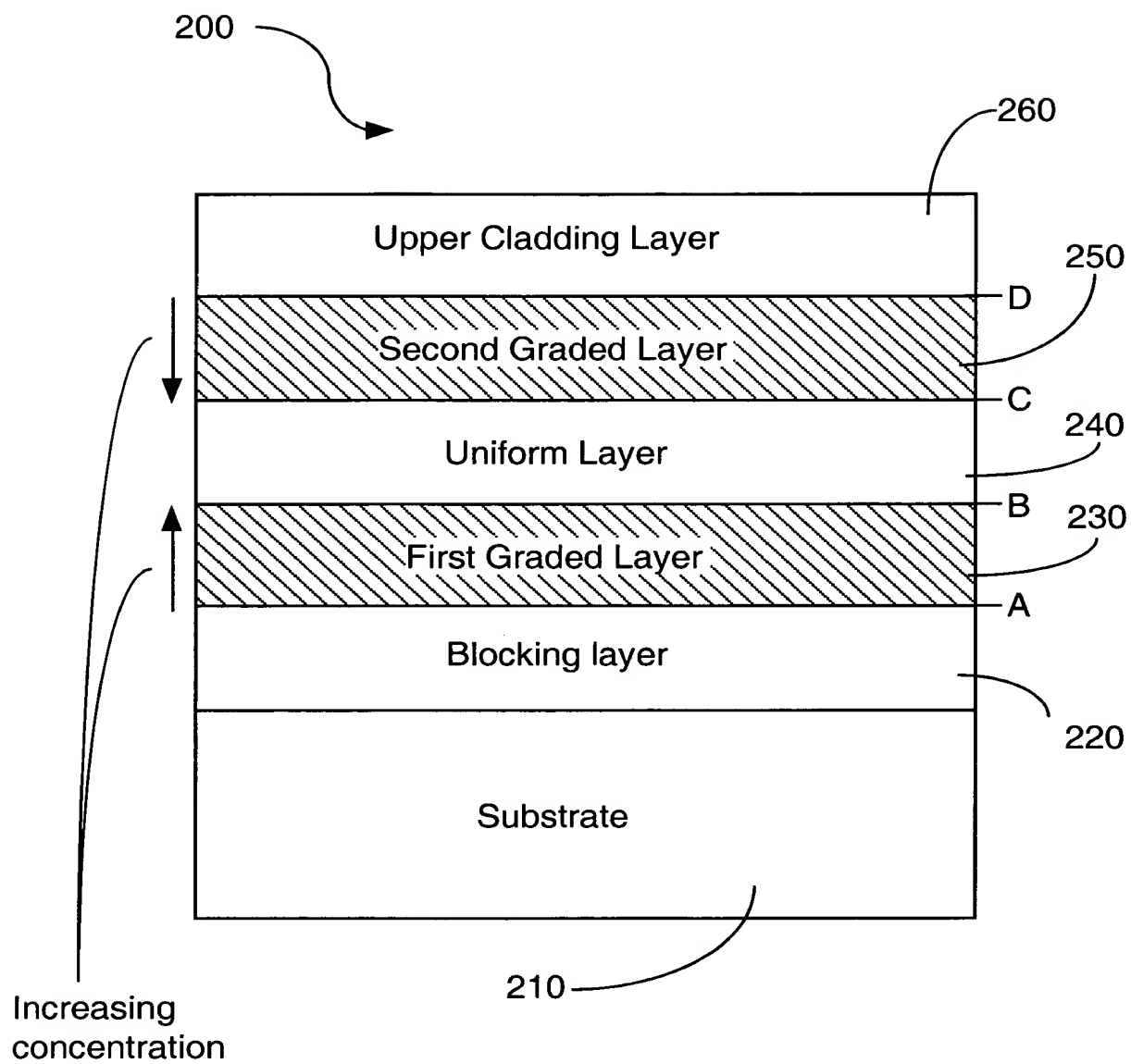


Figure 2

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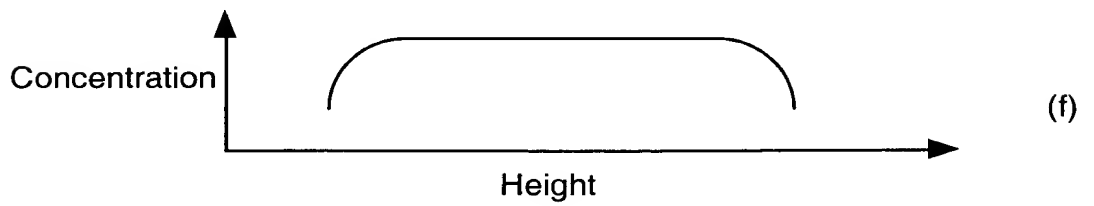
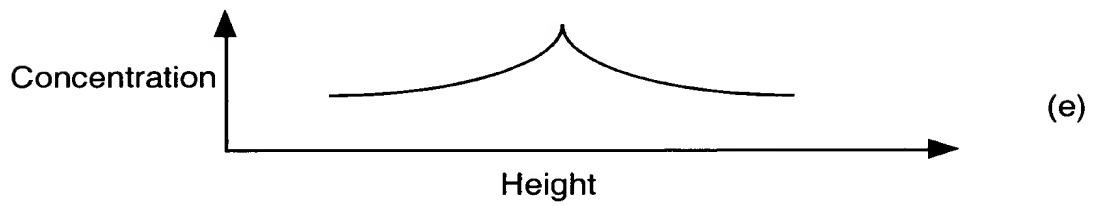
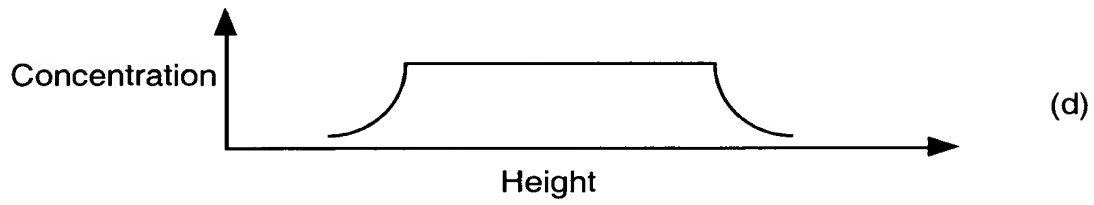
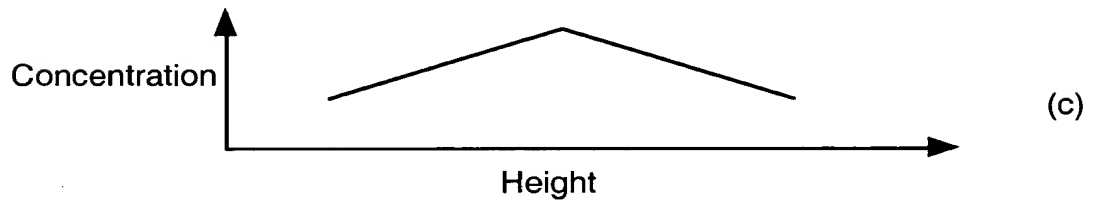
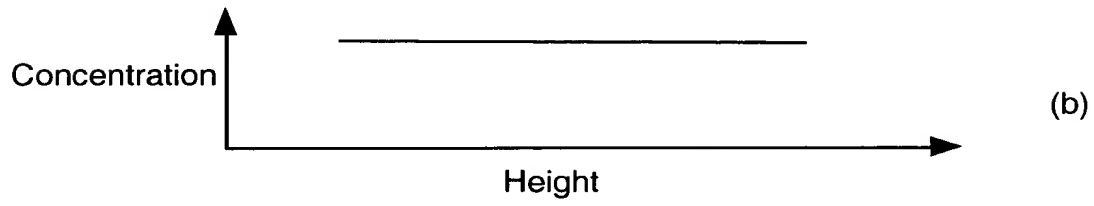
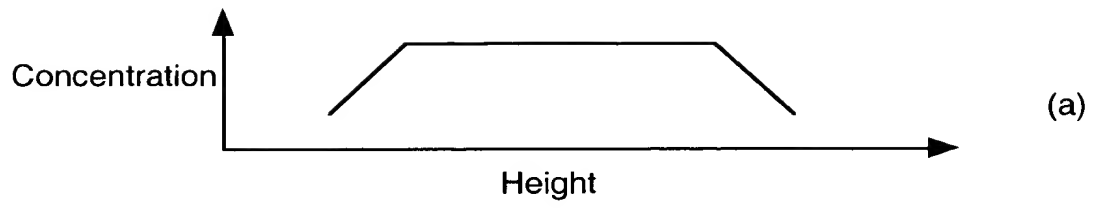
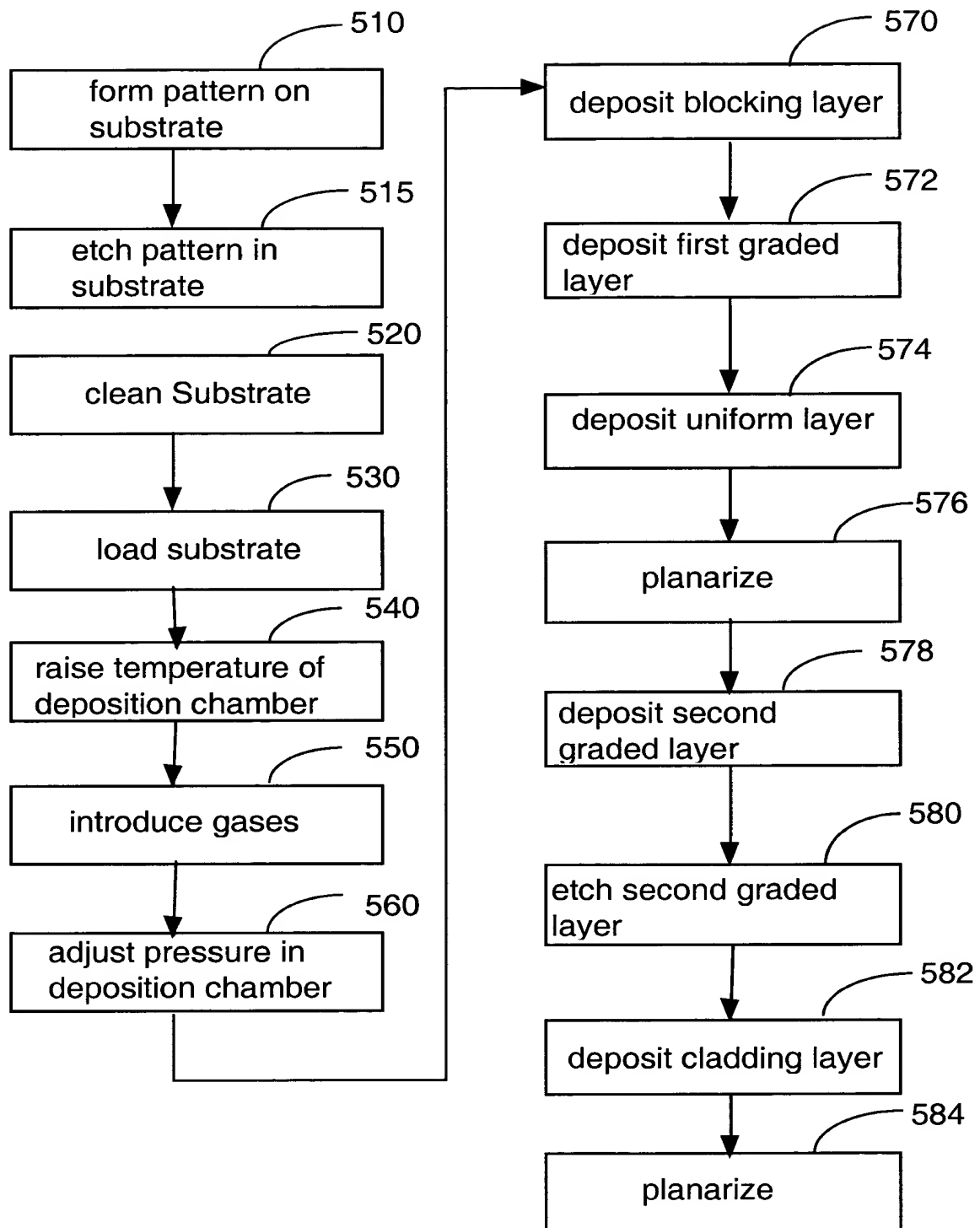


Figure 3

**Figure 4**

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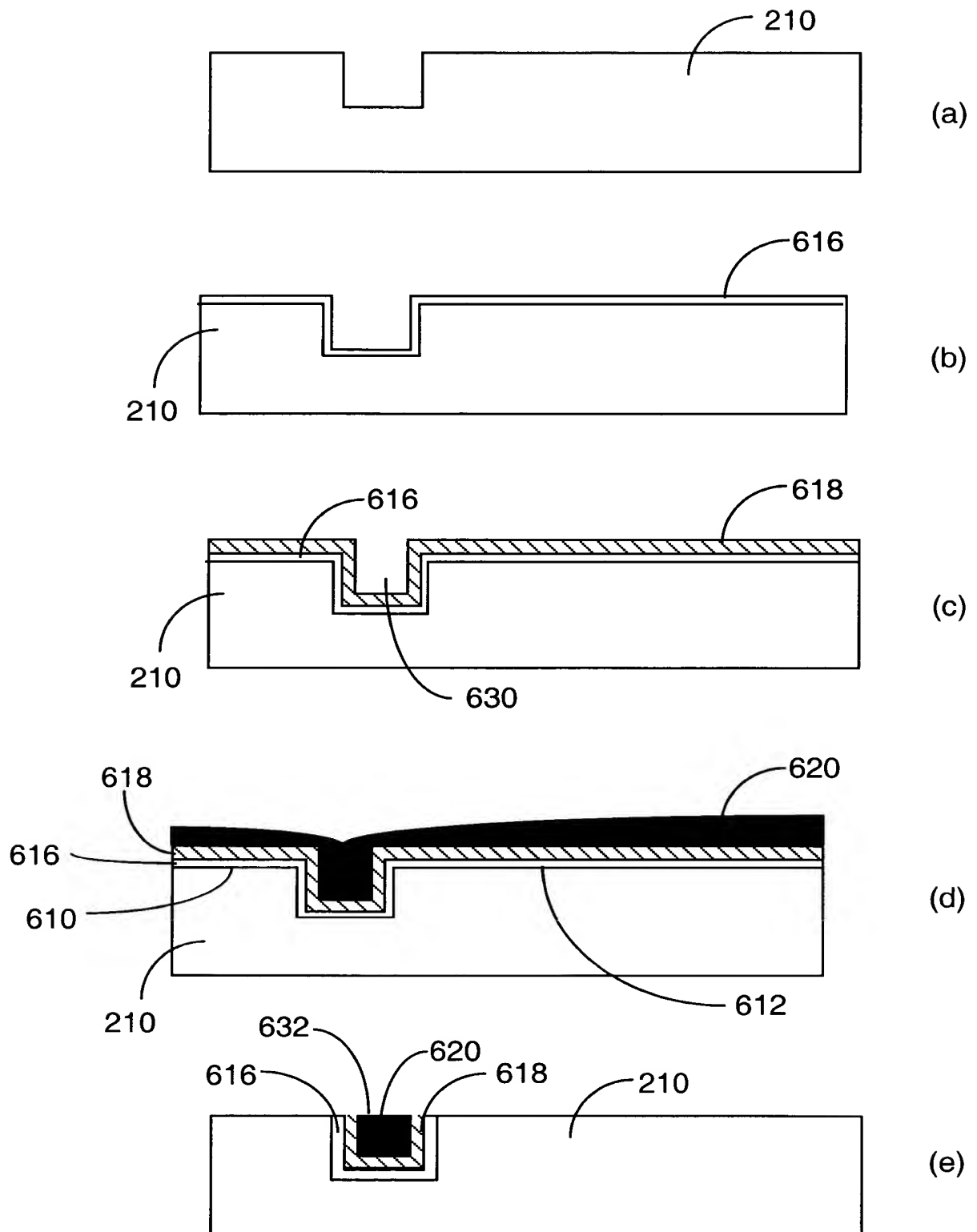


Figure 5

Figure 5 is a schematic diagram of a device 210 in four cross-sectional views (f), (g), (h), and (i) showing different stages of a manufacturing process. The device 210 includes a substrate 616 and a central region 620. In view (f), a layer 618 is formed on the top surface of the substrate 616, and a layer 622 is formed on the top surface of the central region 620. In view (g), the layer 618 is removed from the top surface of the substrate 616, and the layer 622 is formed on the top surface of the central region 620. In view (h), the layer 618 is removed from the top surface of the substrate 616, and the layer 622 is formed on the top surface of the central region 620. In view (i), the layer 618 is removed from the top surface of the substrate 616, and the layer 622 is formed on the top surface of the central region 620. A layer 624 is formed on the top surface of the substrate 616 in views (h) and (i).

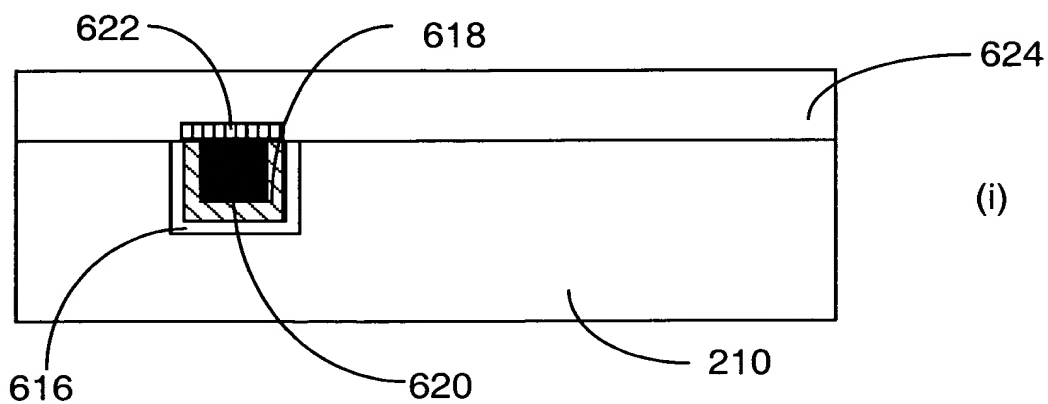
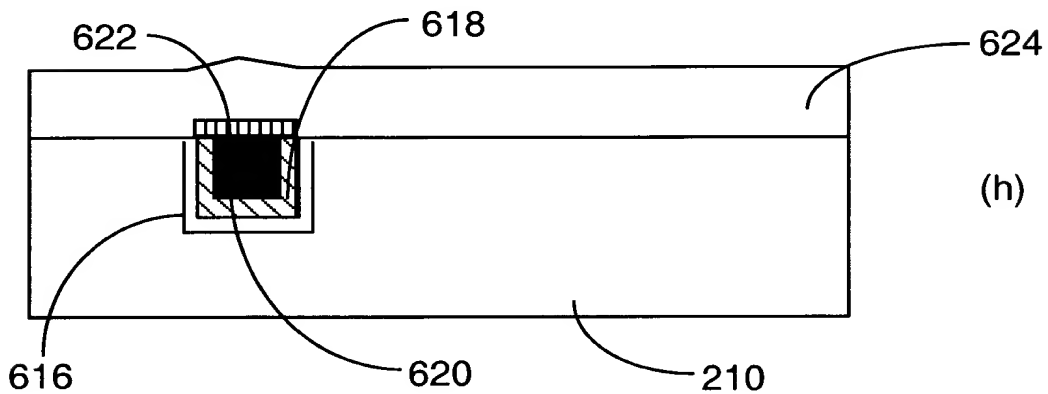
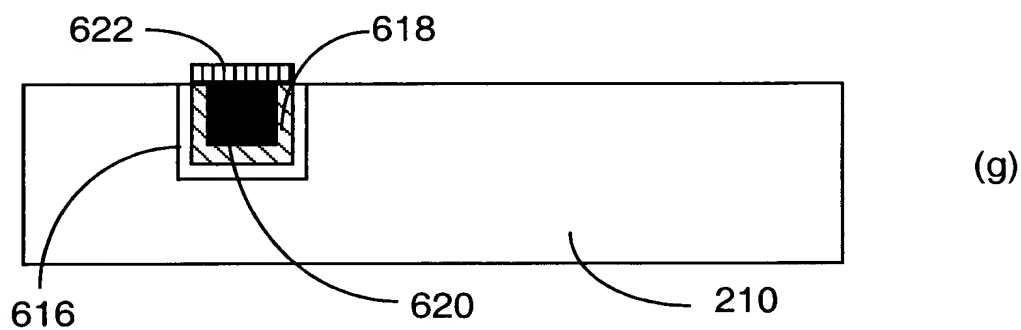
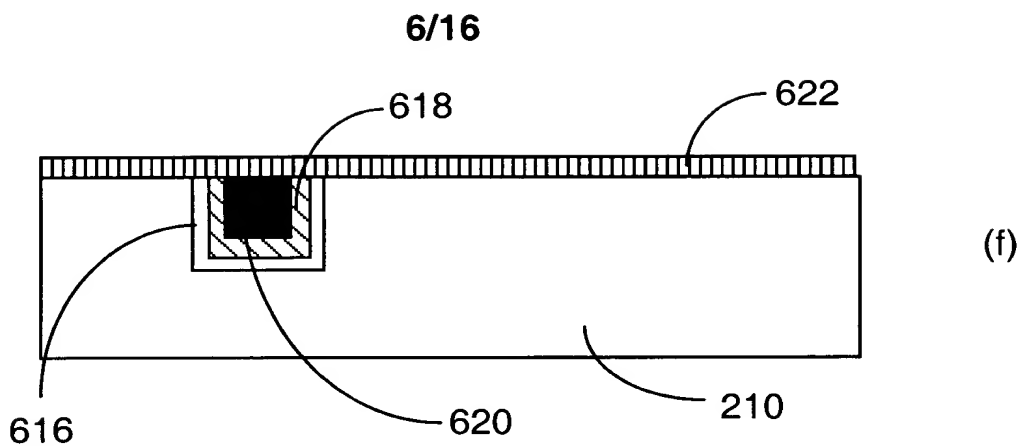
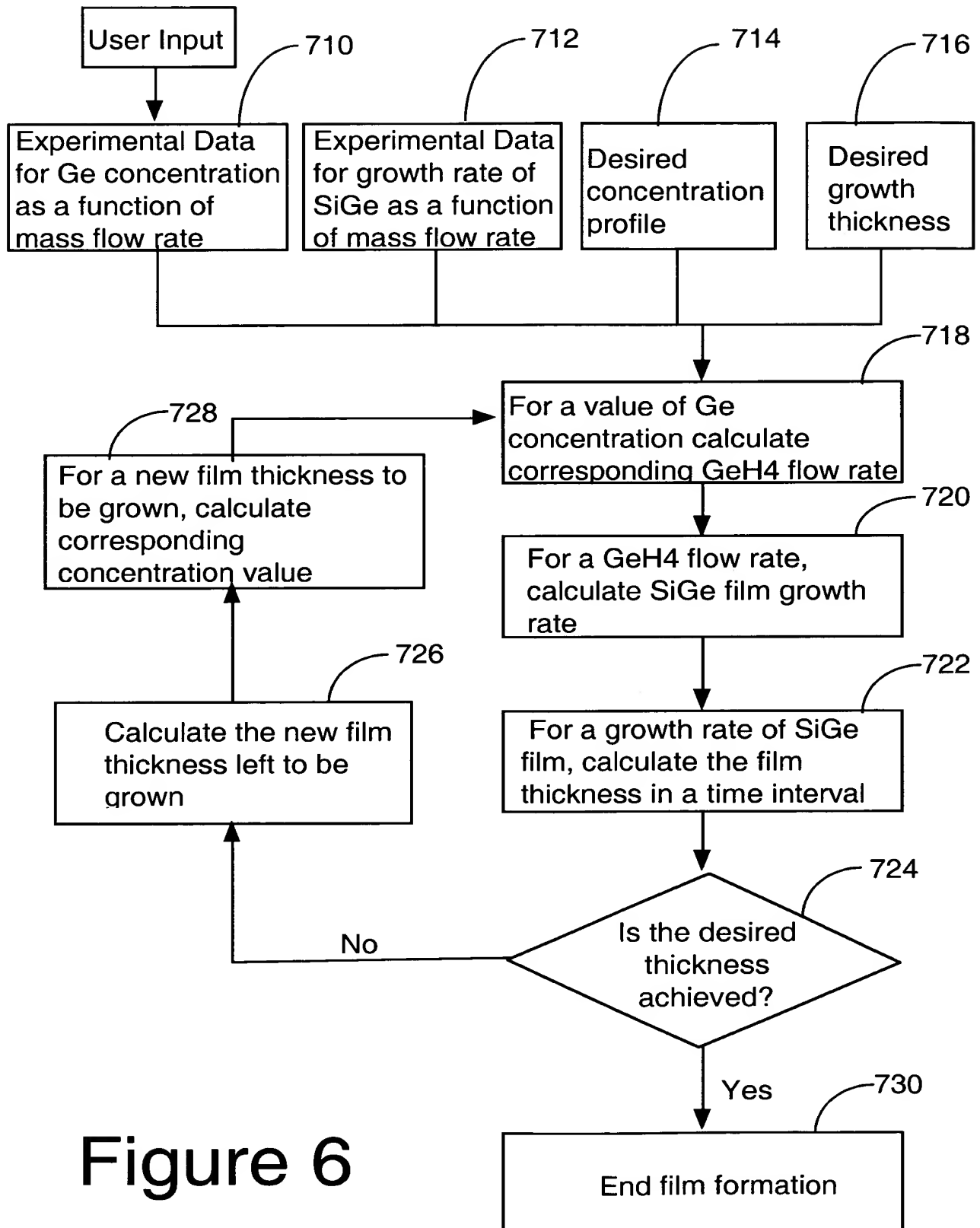
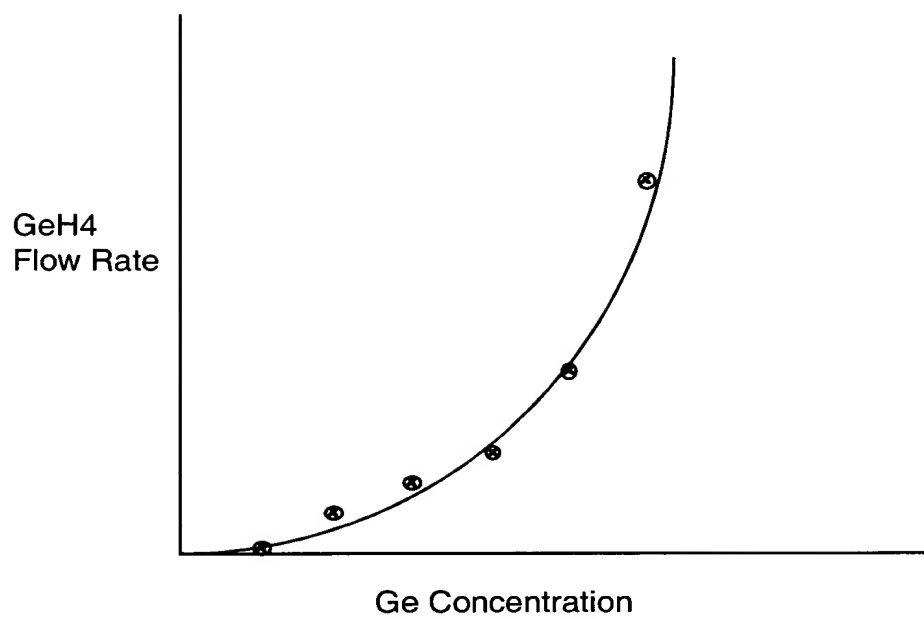
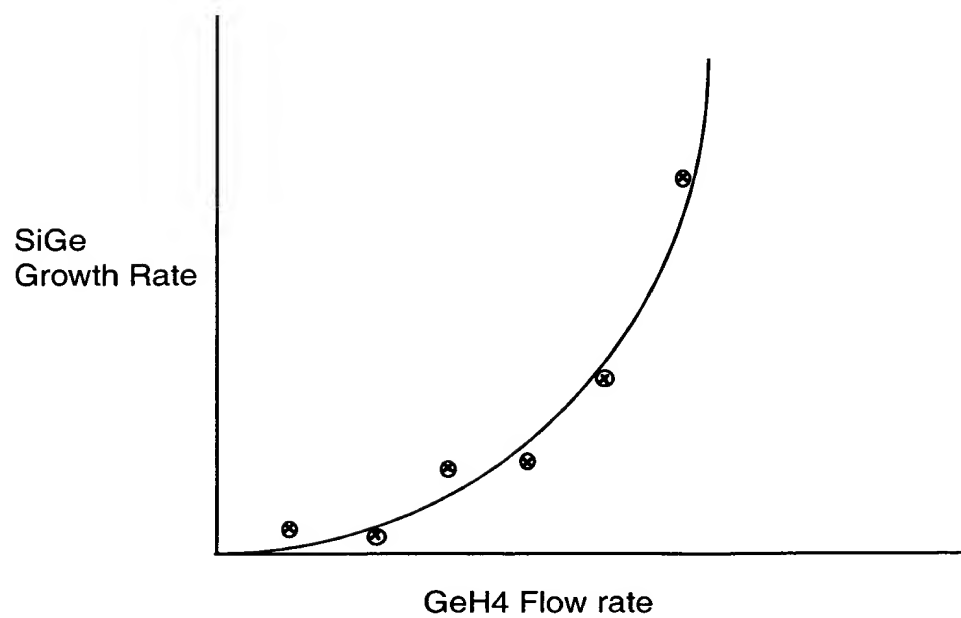


Figure 5

**Figure 6**

**Figure 7****Figure 8**



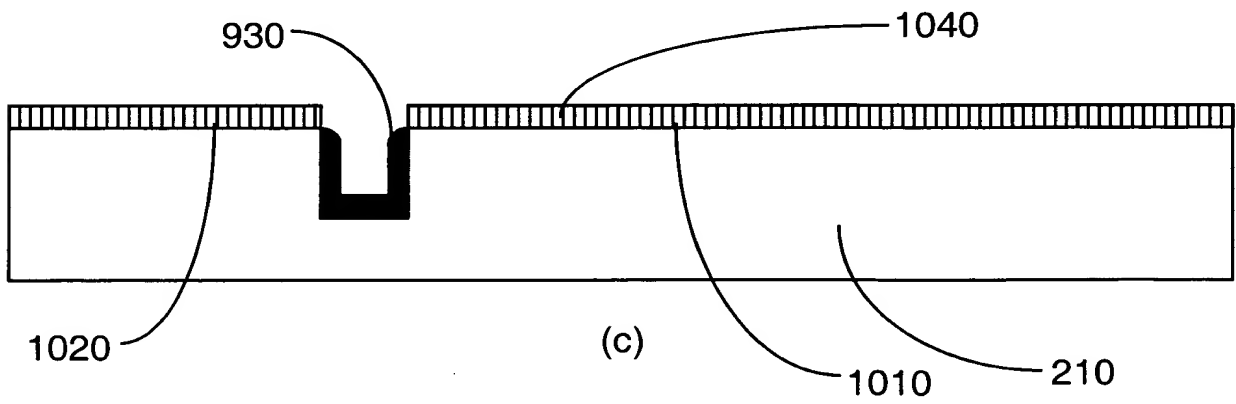
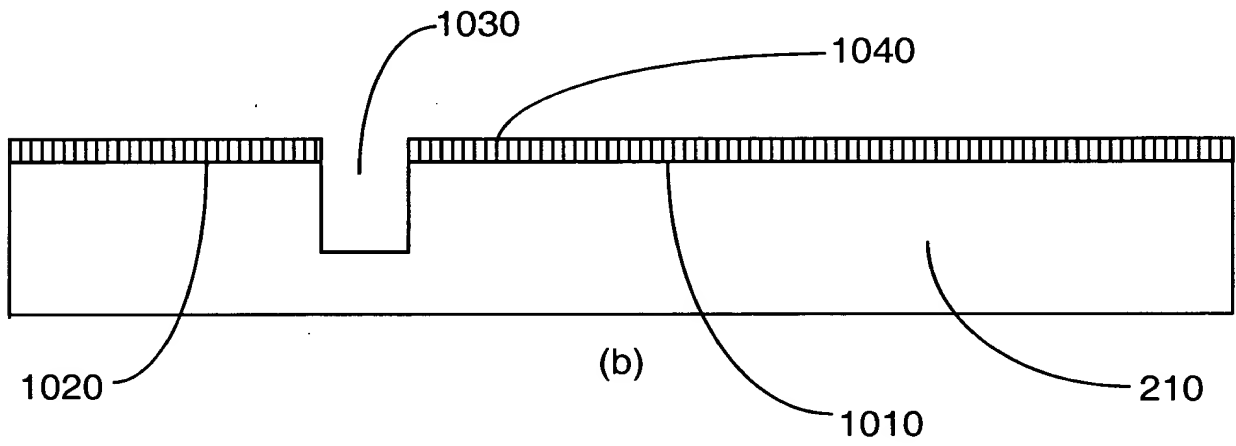
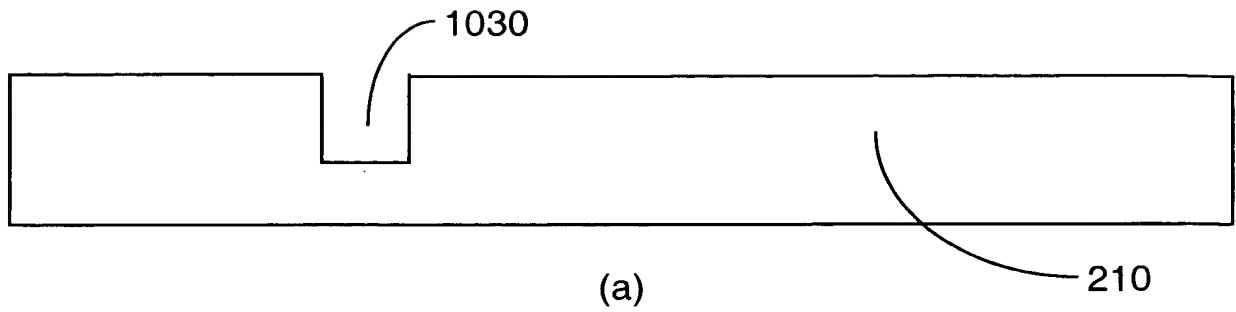


Figure 9

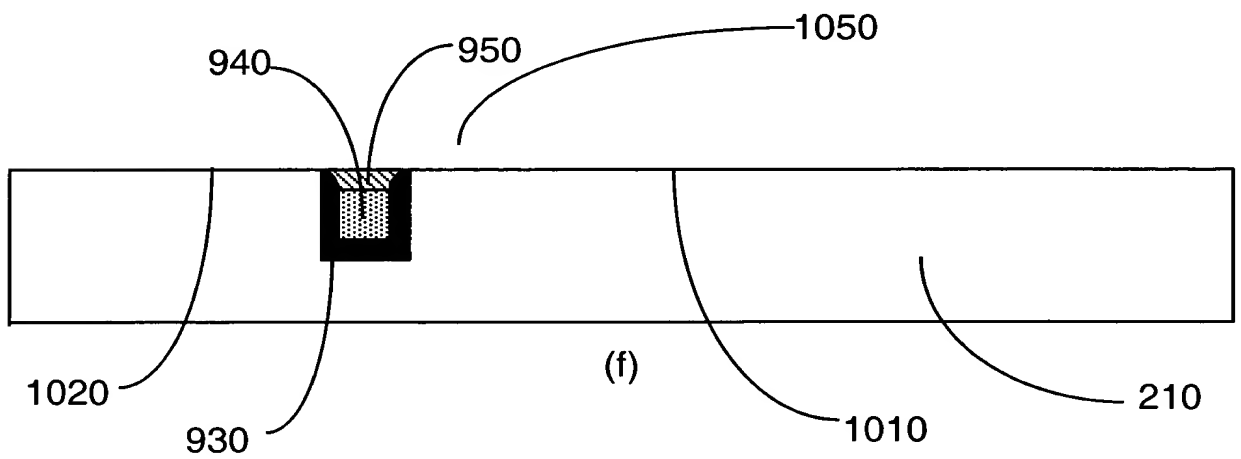
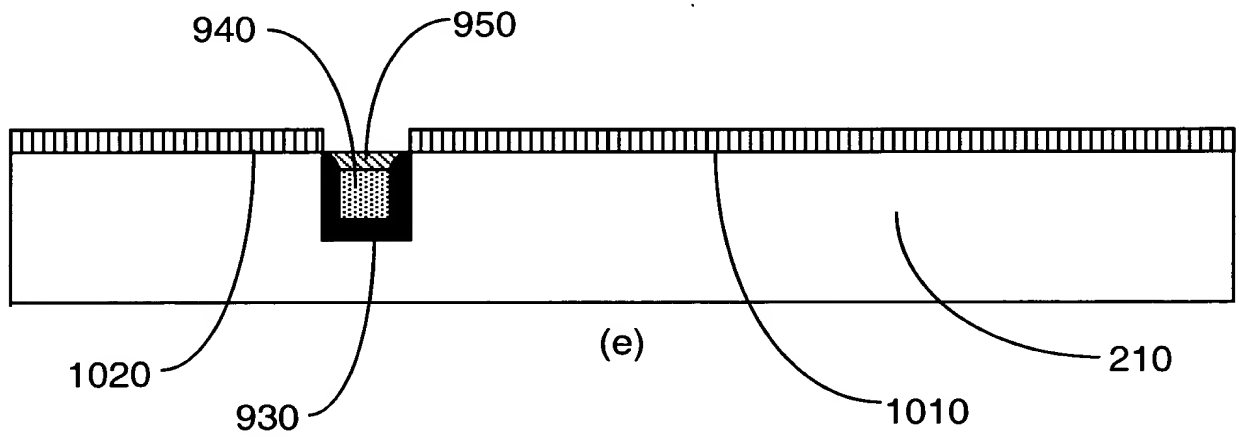
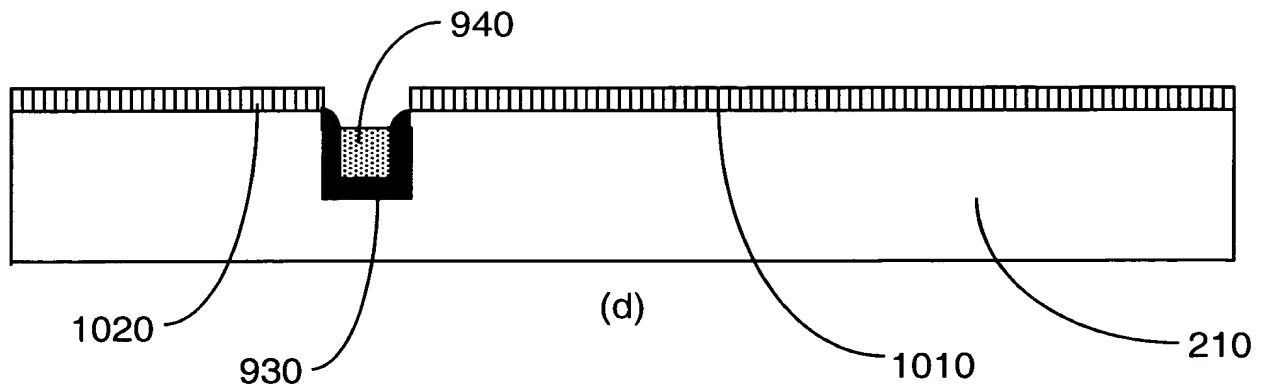
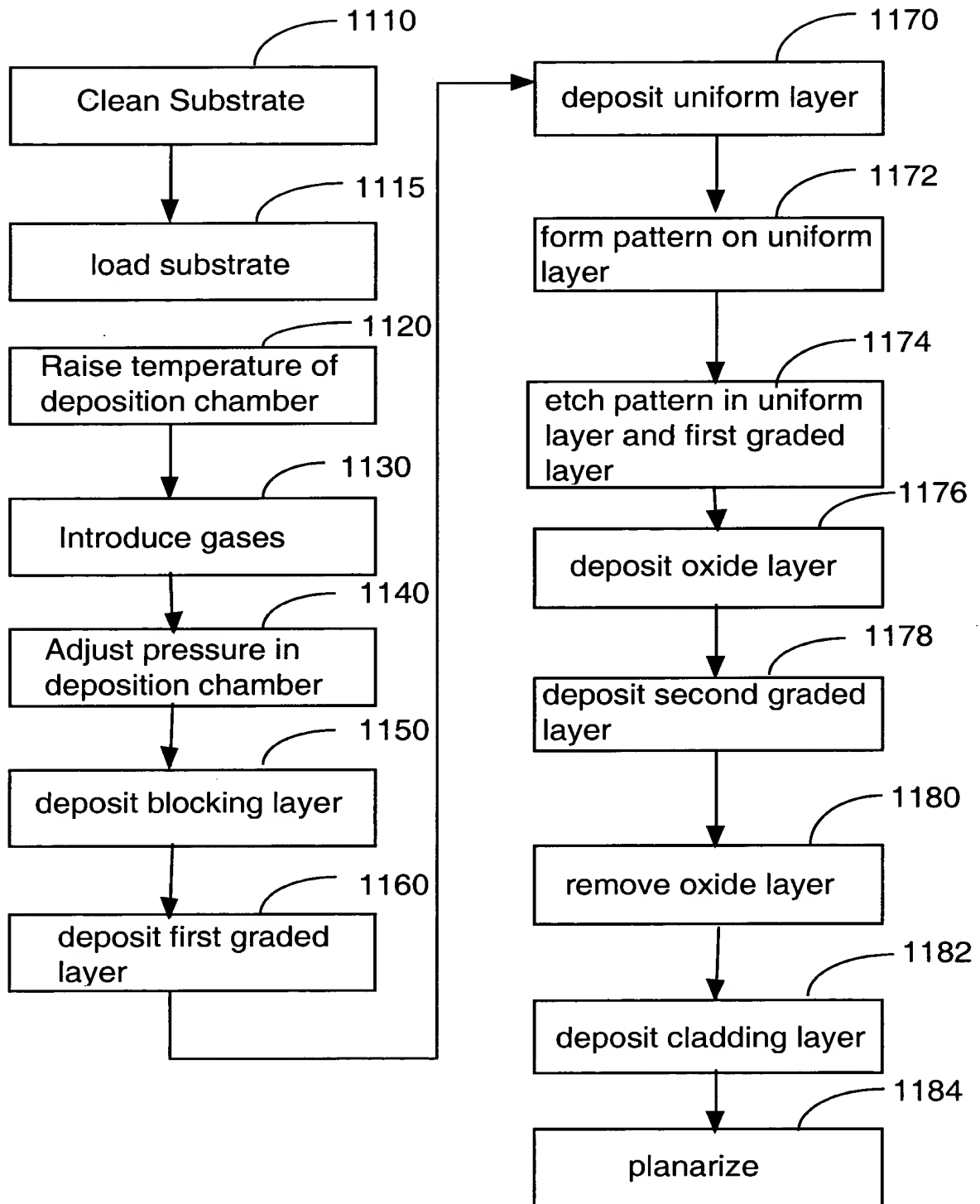


Figure 9

**Figure 10**

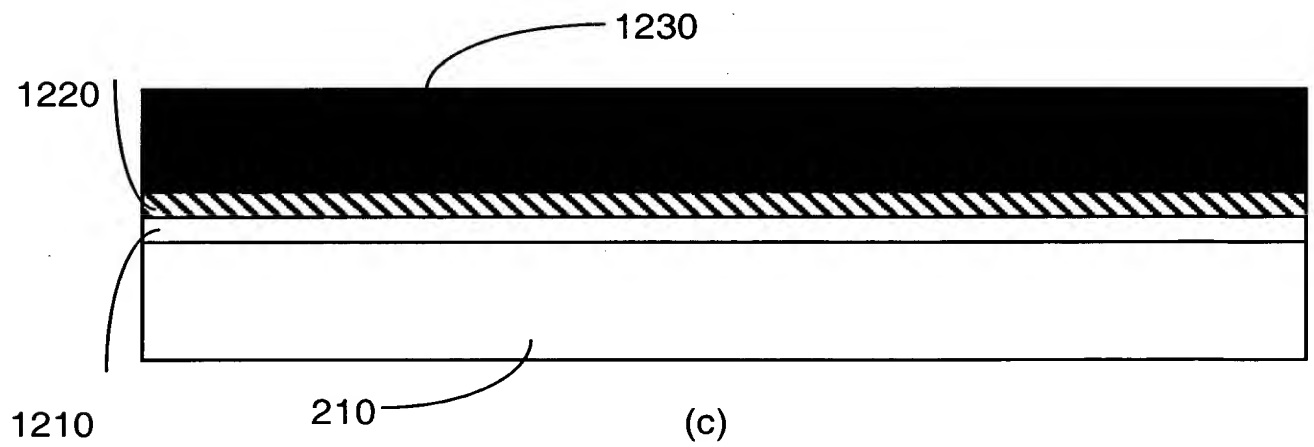
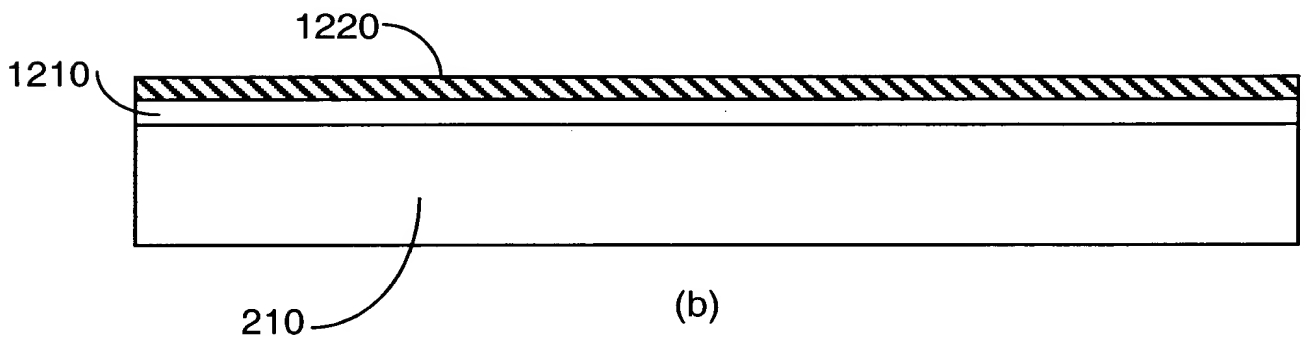
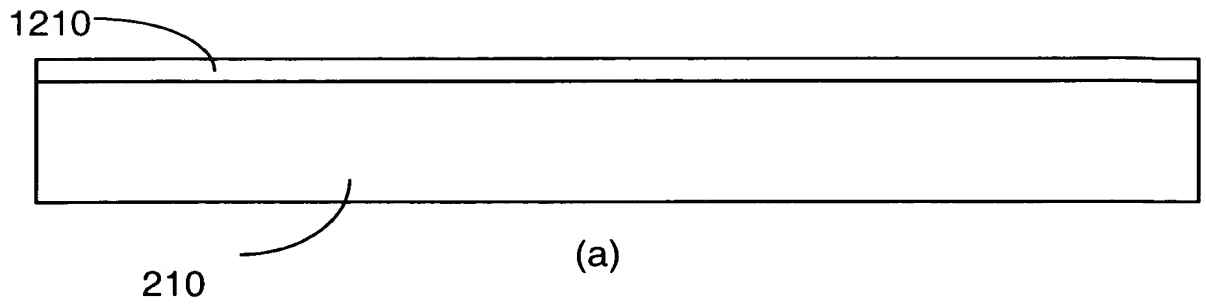


Figure 11

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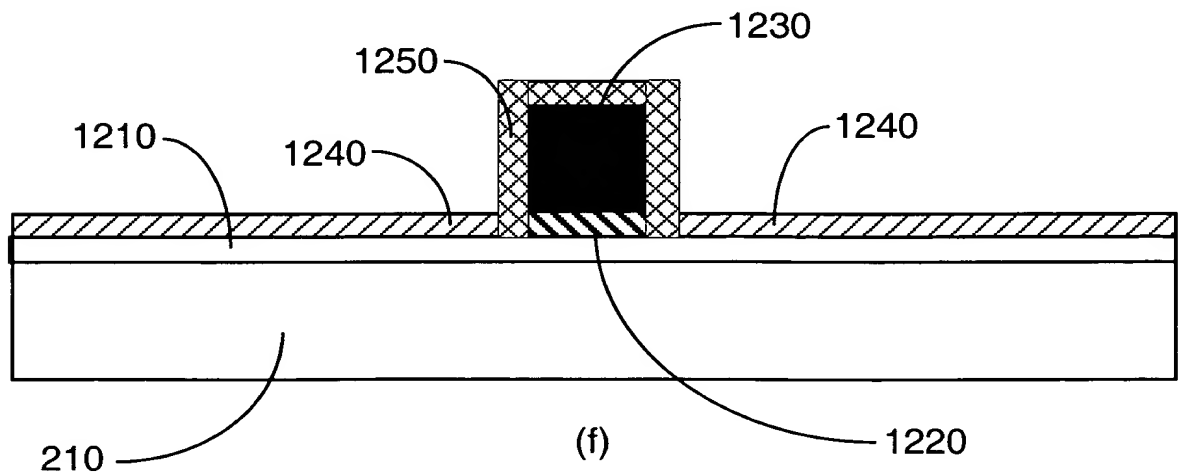
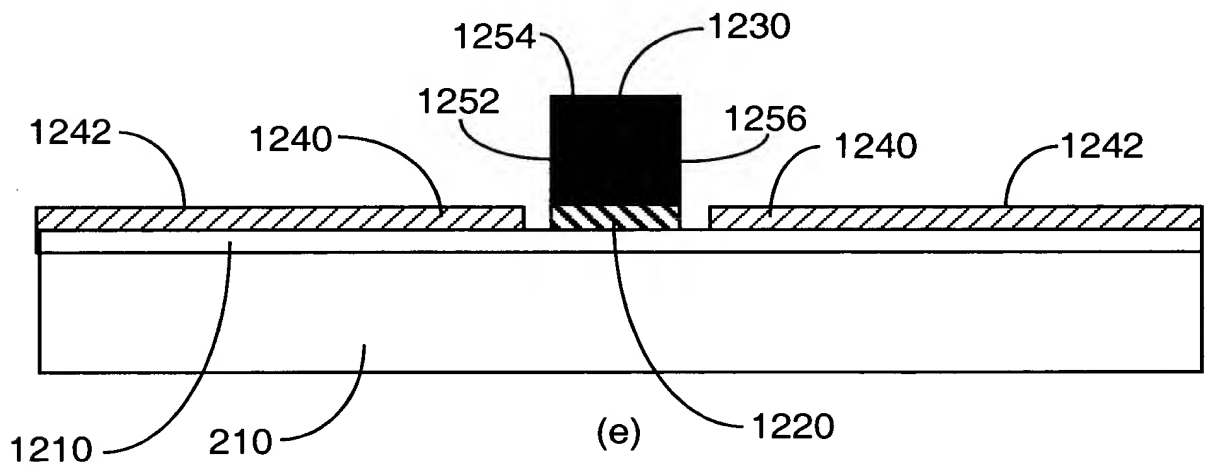
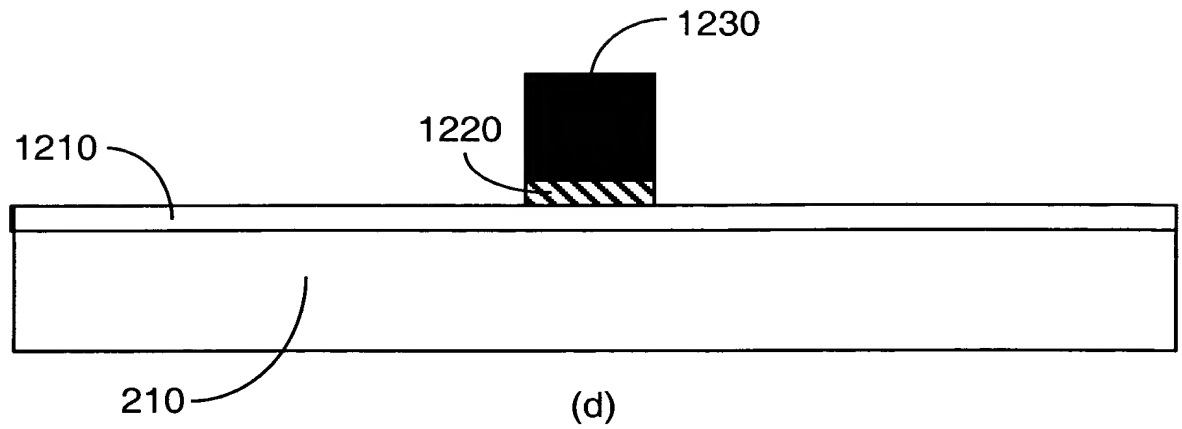


Figure 11

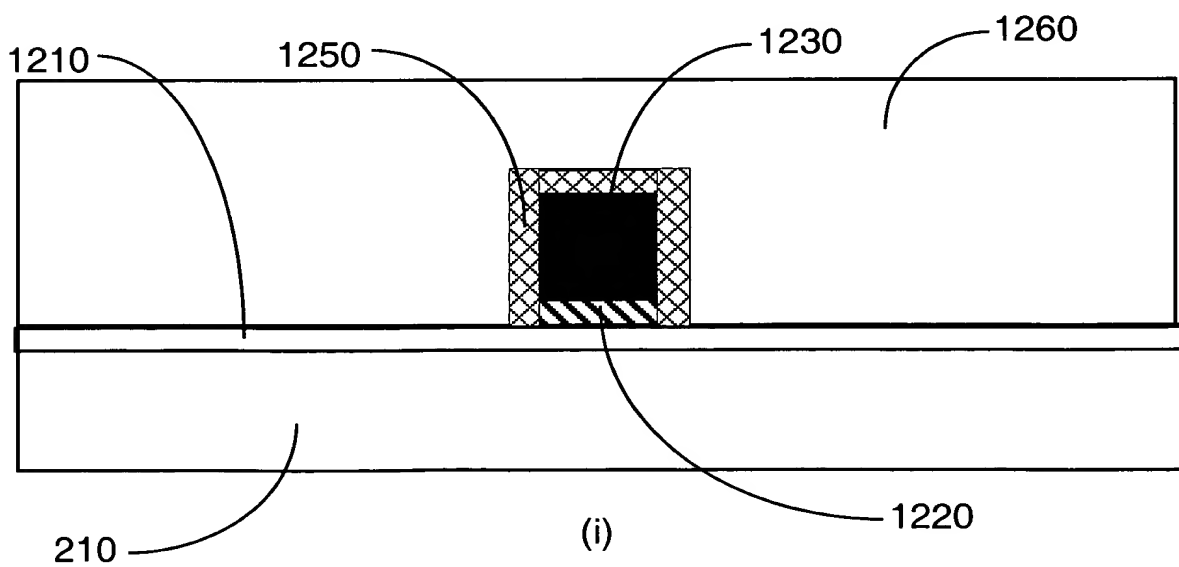
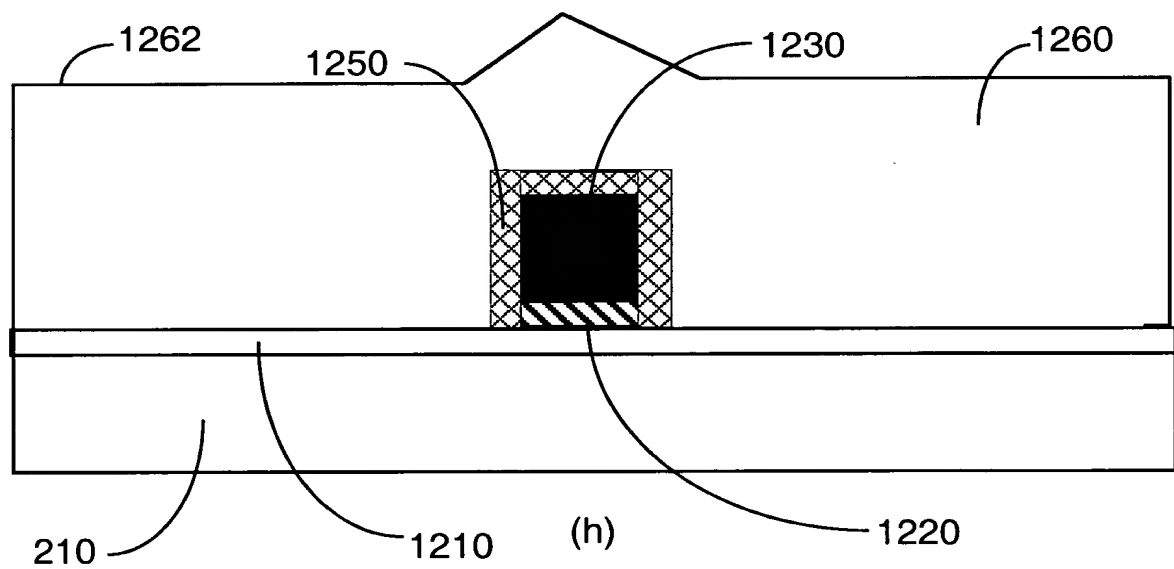
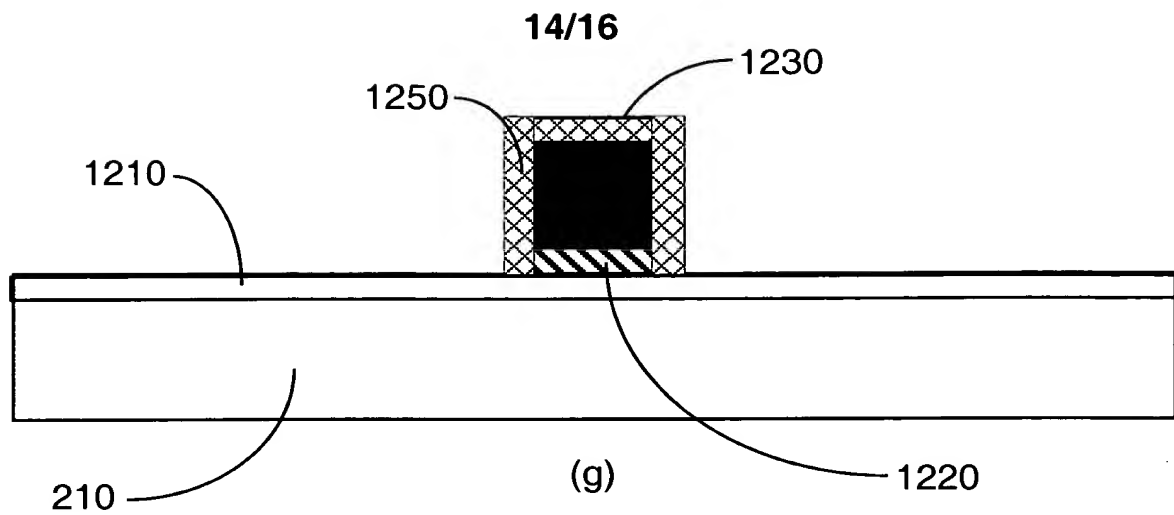


Figure 11

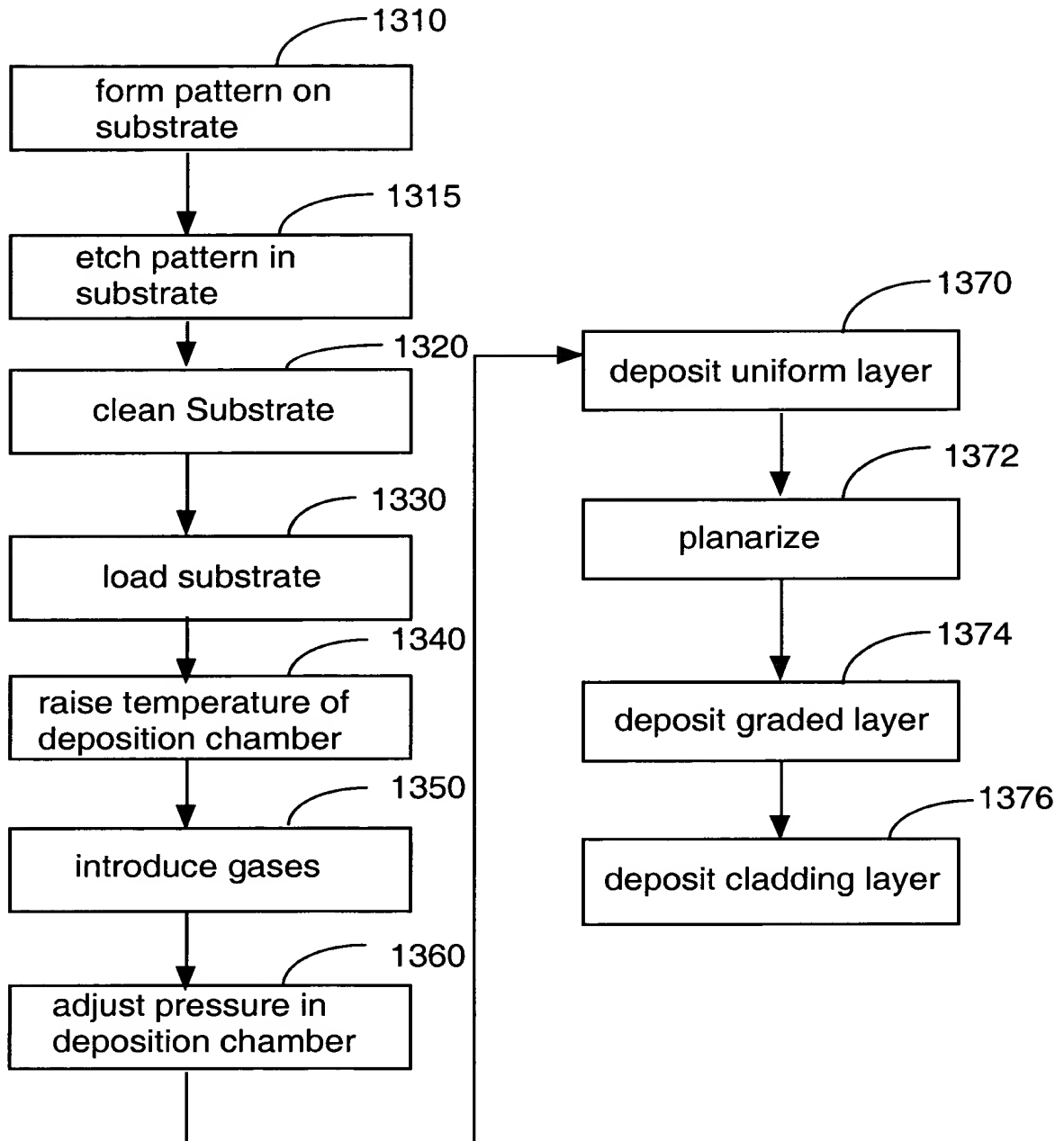


Figure 12

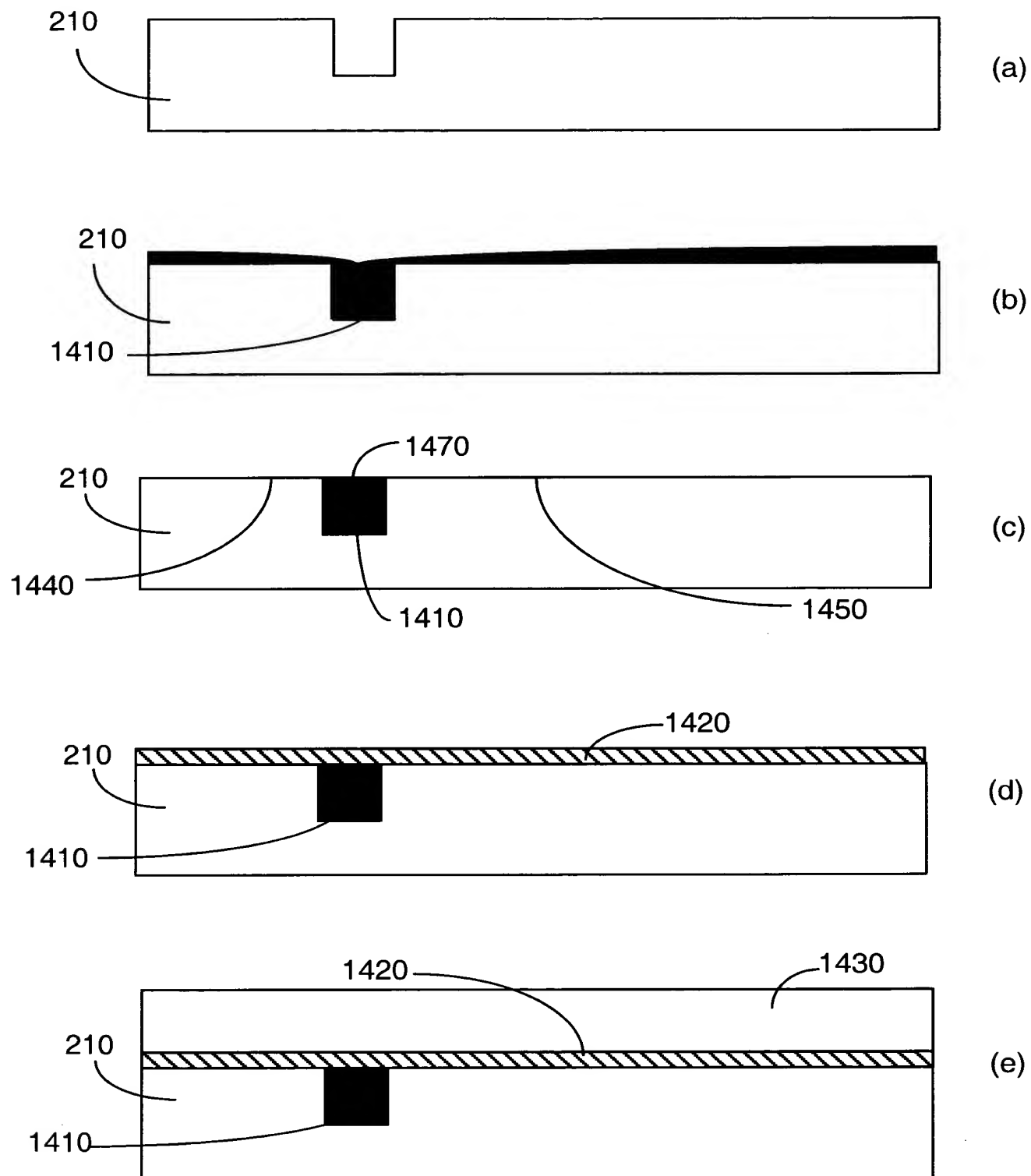


Figure 13